L	Hits	Search Text	DB	Time stamp
Number				
1	1	(29/825.ccls.) and ((component or chip)	USPAT;	2004/09/22
		with reflow) and (ACF or (anisotropic adj	US-PGPUB;	08:28
		conductive adj film)) and ((wiring or	IBM_TDB	
2	. 1	circuit) adj board) ("6553660").PN.	USPAT;	2004/09/22
12	*	( 0333000 ).FM.	US-PGPUB;	08:27
			IBM TDB	""
3	7	(29/830,833,835,840).ccls. and	USPAT;	2004/09/22
		((component or chip) with reflow) and	US-PGPUB;	08:30
		(ACF or (anisotropic adj conductive adj	IBM_TDB	
		film)) and ((wiring or circuit) adj		
1.		board)		0004/00/00
4	3		USPAT;	2004/09/22
		with reflow) and (ACF or (anisotropic adj conductive adj film)) and ((wiring or	US-PGPUB; IBM TDB	08:31
		circuit) adj board)	154-155	
5	3		USPAT;	2004/09/22
•		chip) with reflow) and (ACF or	US-PGPUB;	08:31
	İ	(anisotropic adj conductive adj film))	IBM_TDB	
		and ((wiring or circuit) adj board)	_	
9	8	("5592025"   "5612576"   "5726489"	USPAT	2004/09/22
		"5736789"   "5834835"   "6016013"		08:32
		"6057597"   "6064114").PN.	HCDATE.	2004/00/21
-	2	(("6,222,281") or ("6,265,770")).PN.	USPAT; US-PGPUB;	2004/09/21
			IBM TDB	11.52
_	1	(kobayashi-yukihisa).in.	USPAT;	2004/09/21
	1	(Nobalabile Janilisa) (2019)	US-PGPUB;	09:40
			IBM TDB	
-	313	reflow and (ACF or (anisotropic adj	USPĀT;	2004/09/21
		conductive adj film))	US-PGPUB;	11:53
			IBM_TDB	0004/00/01
-	218	reflow and (ACF or (anisotropic adj	USPAT;	2004/09/21
		conductive adj film)) and ((wiring or circuit) adj board)	US-PGPUB; IBM TDB	11:54
1_	73	((component or chip) with reflow) and	USPAT;	2004/09/21
	, ,	(ACF or (anisotropic adj conductive adj	US-PGPUB;	18:39
		film)) and ((wiring or circuit) adj	IBM TDB	
		board)	_	
-	19		USPAT;	2004/09/21
		((ACF or (anisotropic adj conductive adj	US-PGPUB;	13:52
1		film)) with (conductive adj particle))	IBM_TDB	
	1	and ((wiring or circuit) adj board) (component or chip) and reflow same ((ACF	USPAT;	2004/09/21
1		or (anisotropic adj conductive adj film))	US-PGPUB;	13:53
1		with (conductive adj particle)) and	IBM TDB	
1		((wiring or circuit) adj board)		
-	74	(component or chip) and reflow and ((ACF	USPAT;	2004/09/21
1		or (anisotropic adj conductive adj film))	US-PGPUB;	14:00
1		with (conductive adj particle)) and	IBM_TDB	
		((wiring or circuit) adj board)	HCD2m.	2004/00/21
-	57	(component or chip) and (solder with reflow) and ((ACF or (anisotropic adj	USPAT; US-PGPUB;	2004/09/21
1		conductive adj film)) with (conductive	IBM TDB	17.01
		adj particle)) and ((wiring or circuit)	10.1_100	
		adj board)		
-	9	("5502889"   "5525205"   "5679730"	USPAT	2004/09/21
		"5727310"   "5822030"   "5861661"		14:26
		"5978203"   "6111628"   "6190578").PN.		
-	8	(29/832.ccls.) and ((component or chip)	USPAT;	2004/09/21
		with reflow) and (ACF or (anisotropic adj	US-PGPUB;	18:44
		conductive adj film)) and ((wiring or circuit) adj board)	IBM_TDB	[ ] [ ]
I		CIICUIC, au DOAIU,	l	